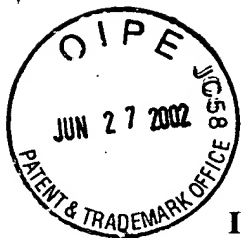


2826

07-01-02



PATENTS
112055-0040

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:)
David Chong et al.)
Serial No.: 09/823,600)
Filed: March 30, 2001)
For: PACKAGING SYSTEM FOR DIE-)
UP CONNECTION OF A DIE-)
DOWN ORIENTED INTEGRATED)
CIRCUIT)

Examiner: Andujar, Leonardo

Art Unit: Not yet assigned

Cesari and McKenna, LLP
88 Black Falcon Avenue
Boston, MA 02210
June 27, 2002

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X Amendment



PATENTS
112055-0040

#9/Amend a
April
7/14/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re The Application of:)
David Chong et al.)
Serial No.: 09/823,600)
Filed: March 30, 2001)
For: PACKAGING SYSTEM FOR)
DIE-UP CONNECTION OF A)
DIE-DOWN ORIENTED INTE-)
GRATED CIRCUIT)

Examiner: Andujar, Leonardo

Art Unit: 2826

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Cesari and McKenna, LLP
88 Black Falcon Avenue
Boston, MA 02210
June 27, 2002

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Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

AMENDMENT

This is in response to an Office Action dated 4/10/2002 that rejected the elected claims 1-8. This response is being timely filed within the three month period and no new fees are due.

Please amend independent claim 1, as follows:

~~Claim 1. (amended) A die attach package for connecting a die-down die in a die-up~~
orientation, the die-down die attach package comprising:
a substrate having a plurality of leads for connection to the die-down die and to a
printed circuit board,

A1